



SOT1985-1

VFBGA36, very thin fine-pitch ball grid array package, 36 terminals, 0.5 mm pitch, 3.5 mm x 3.5 mm x 0.8 mm body

16 July 2018

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	VFBGA36
Package style descriptive code	VFBGA (very thin fine-pitch ball grid array)
Mounting method type	S (surface mount)
Issue date	28-06-2018
Manufacturer package code	98ASA01281D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	3.5	-	mm
package width	-	3.5	-	mm
package height	-	0.8	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	36	-	



2 Package outline

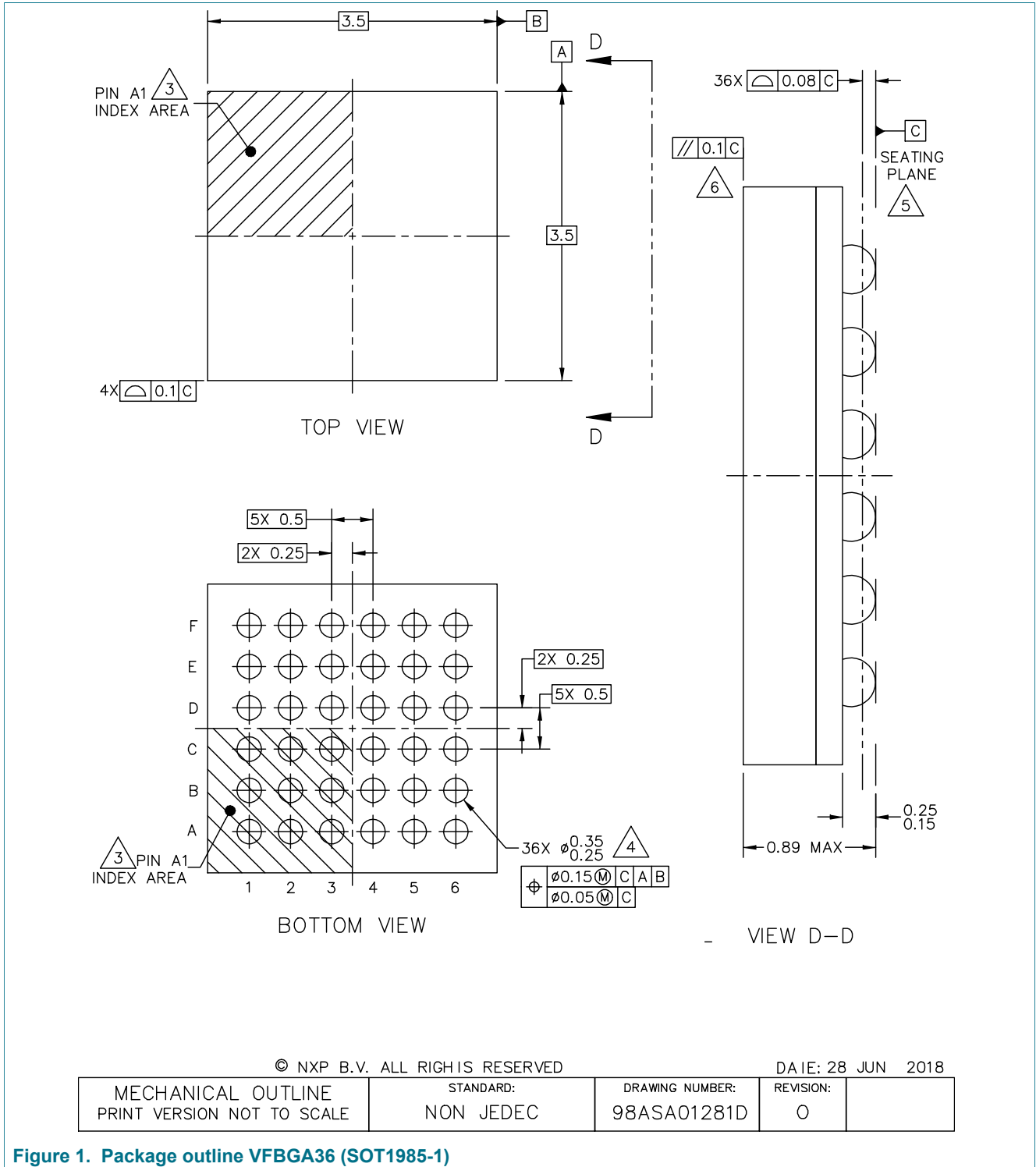


Figure 1. Package outline VFBGA36 (SOT1985-1)

VFBGA36, very thin fine-pitch ball grid array package, 36 terminals, 0.5 mm pitch, 3.5 mm x 3.5 mm x 0.8 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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DATE: 28 JUN 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01281D	REVISION: 0	
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Figure 2. Package outline note VFBGA36 (SOT1985-1)

3 Soldering

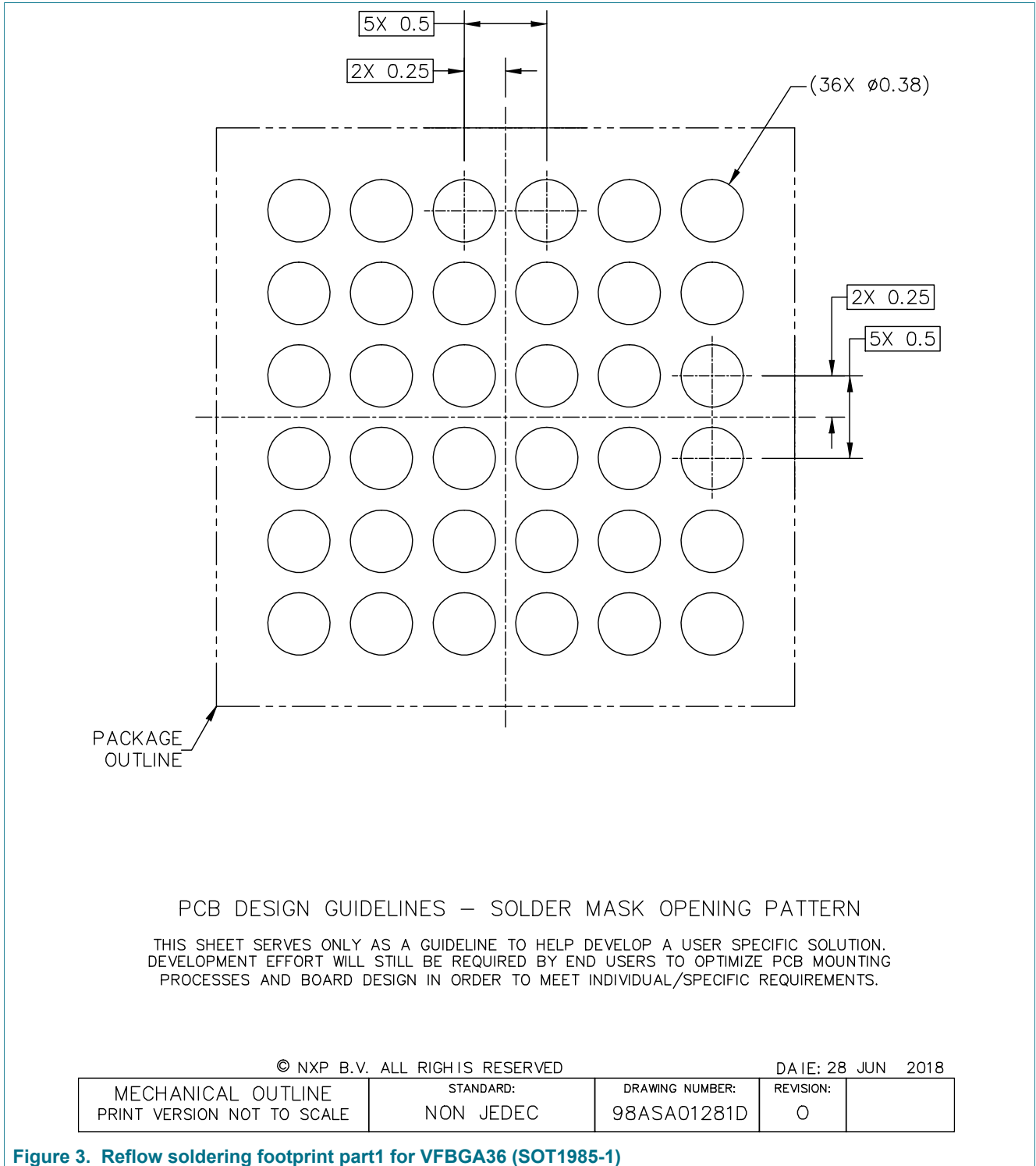


Figure 3. Reflow soldering footprint part1 for VFBGA36 (SOT1985-1)

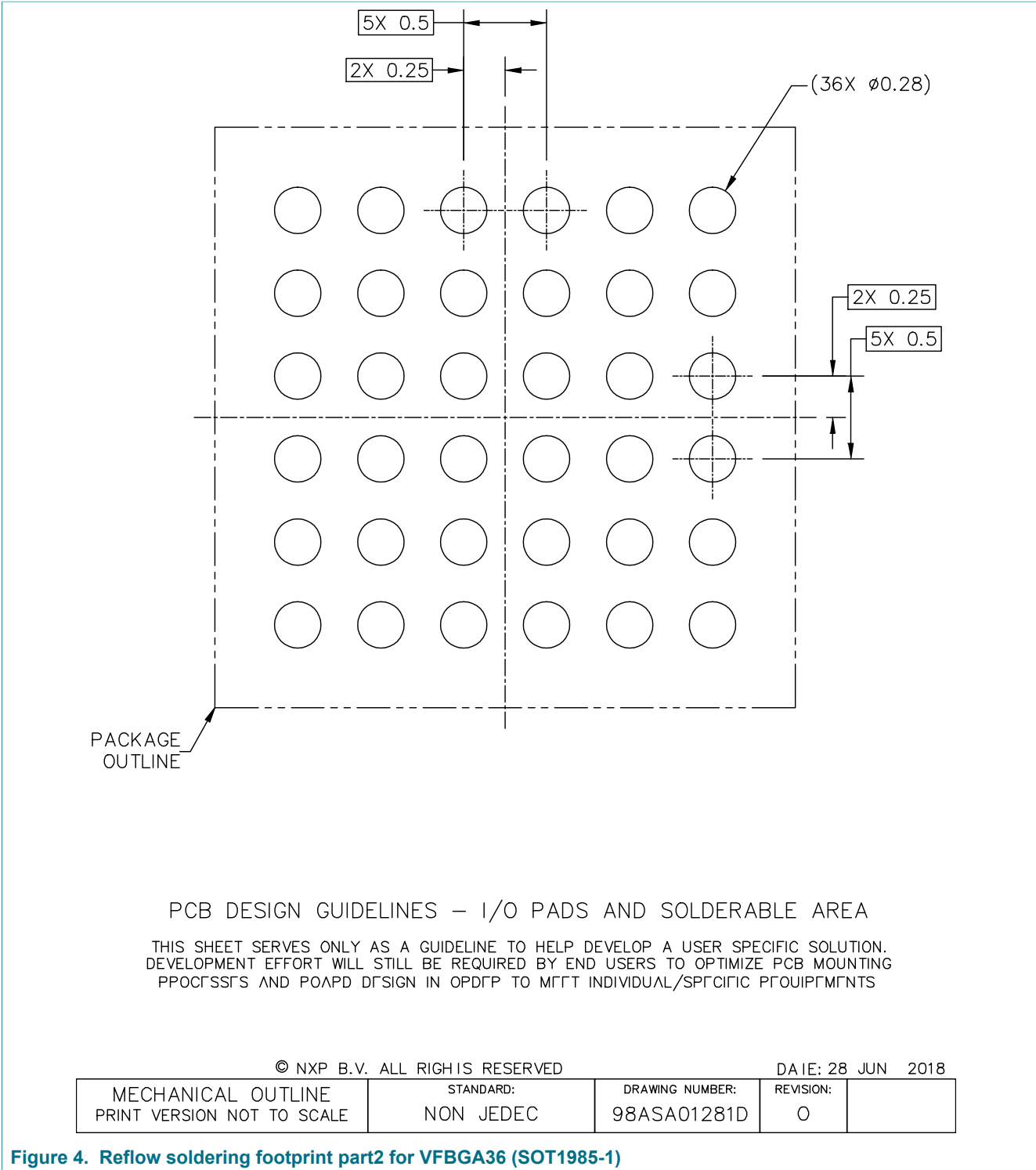


Figure 4. Reflow soldering footprint part2 for VFBGA36 (SOT1985-1)

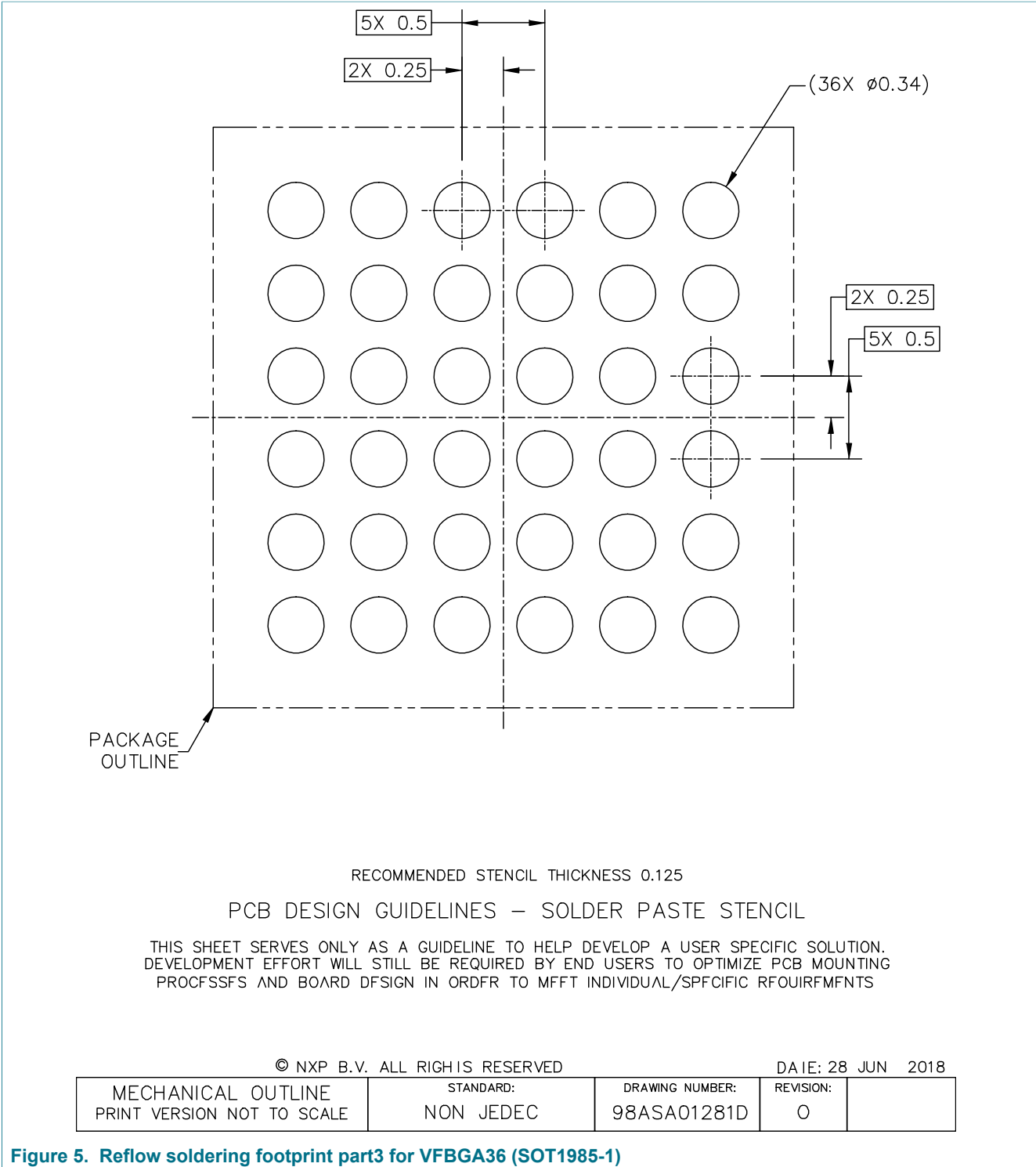


Figure 5. Reflow soldering footprint part3 for VFBGA36 (SOT1985-1)

4 Legal information

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